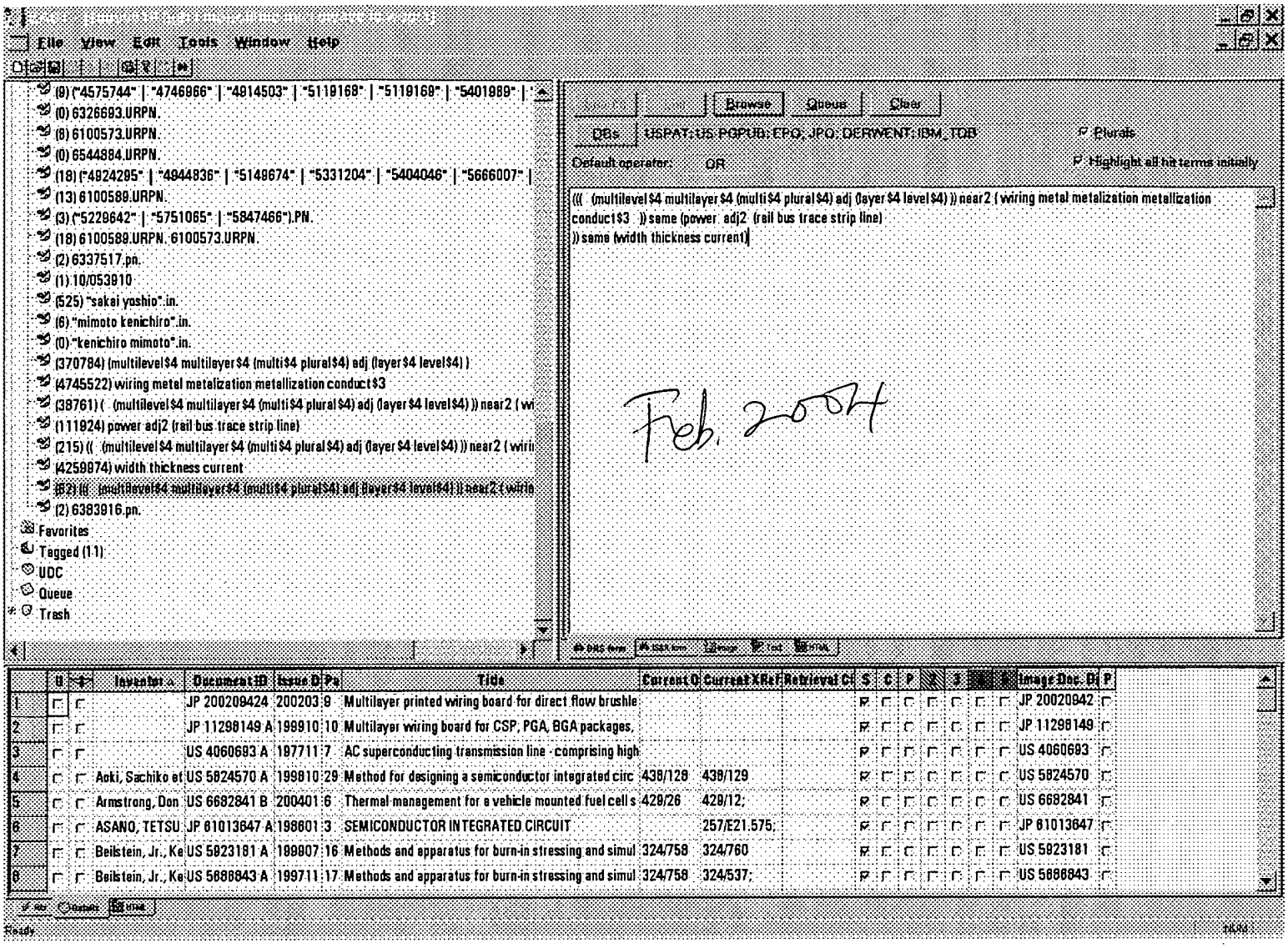

	U		Inventor	Document ID	Issue D	Pa	Title	Current O	Current XRef	Retrieval Cl	S	C	P		3			Image Doc. D	P
1				JP 200209424	200203	9	Multilayer printed wiring board for direct flow brushle											JP 20020942	
2				JP 11298149 A	199910	10	Multilayer wiring board for CSP, PGA, BGA packages,											JP 11298149	
3				US 4060693 A	197711	7	AC superconducting transmission line comprising high											US 4060693	
4			Aoki, Sachiko et	US 5824570 A	199810	29	Method for designing a semiconductor integrated circ	438/128	438/129									US 5824570	
5			Armstrong, Don	US 6682841 B	200401	6	Thermal management for a vehicle mounted fuel cell s	429/26	429/12;									US 6682841	
6			ASANO, TETSU	JP 61013647 A	198601	3	SEMICONDUCTOR INTEGRATED CIRCUIT		257/E21.575;									JP 61013647	
7			Beilstein, Jr., Ke	US 5923181 A	199907	16	Methods and apparatus for burn-in stressing and simul	324/758	324/760									US 5923181	
8			Beilstein, Jr., Ke	US 5686843 A	199711	17	Methods and apparatus for burn-in stressing and simul	324/758	324/537;									US 5686843	